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W.B.

GP/2822

W. A. Dapton

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Rich Fogal and Michael B. Ball	§	
Serial No.: 09/422,887	§	Group Art Unit: 2822
Filed: October 21, 1999	§	Examiner: J. Davis
For: ANGULARLY OFFSET STACKED DIE MULTICHIP DEVICE AND METHOD OF MANUFACTURE	§	Atty. Docket: 95-0134.05
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W. A. Dapton

FIRST AMENDMENT AND RESPONSE TO THE
OFFICE ACTION DATED MAY 24, 2000

Certificate of Mailing (37 C.F.R. § 1.8)

Assistant Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below

9-24-00 *Rich Fogal - Sender*

Date Signature

Applicants herein respond to the Office Action of May 24, 2000. Please amend the above-captioned application as follows.

IN THE SPECIFICATION:

Please delete the following text added in the Preliminary Amendment,

“Related Applications

This application is a divisional of application serial number 09/122,666, filed July 24, 1998; which is a continuation of application serial number 08/741,579, filed November 1, 1996 and issued on February 23, 1999 as U.S. Patent No. 5,874,781; which is a continuation of application serial number 08/515,719, filed August 16, 1995 and now abandoned.”

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